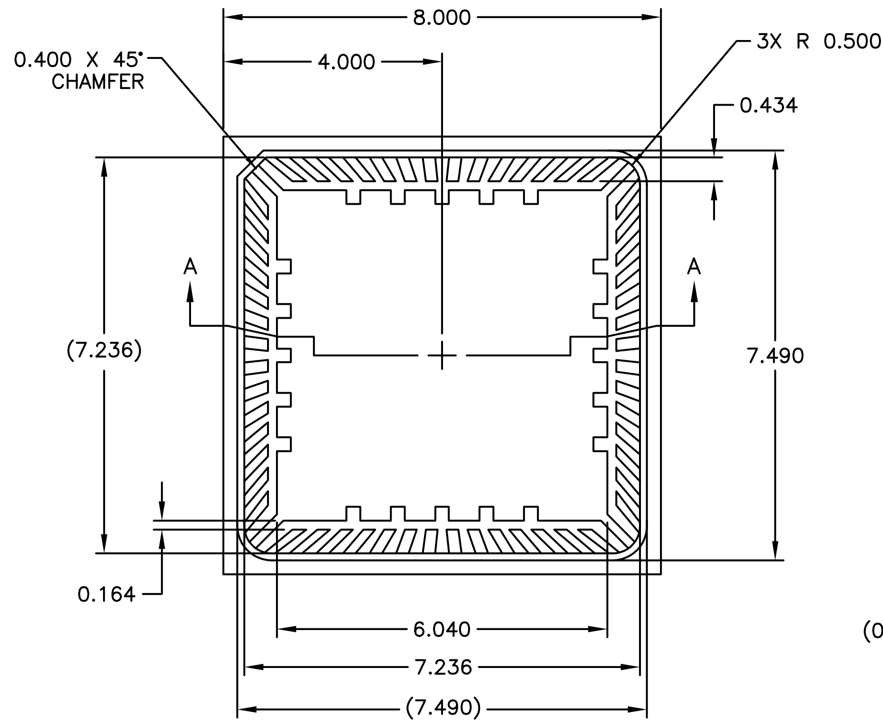
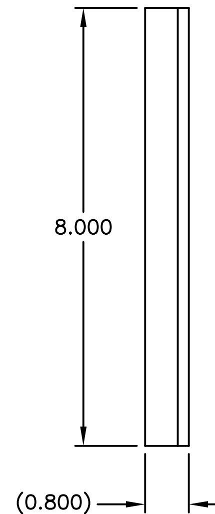
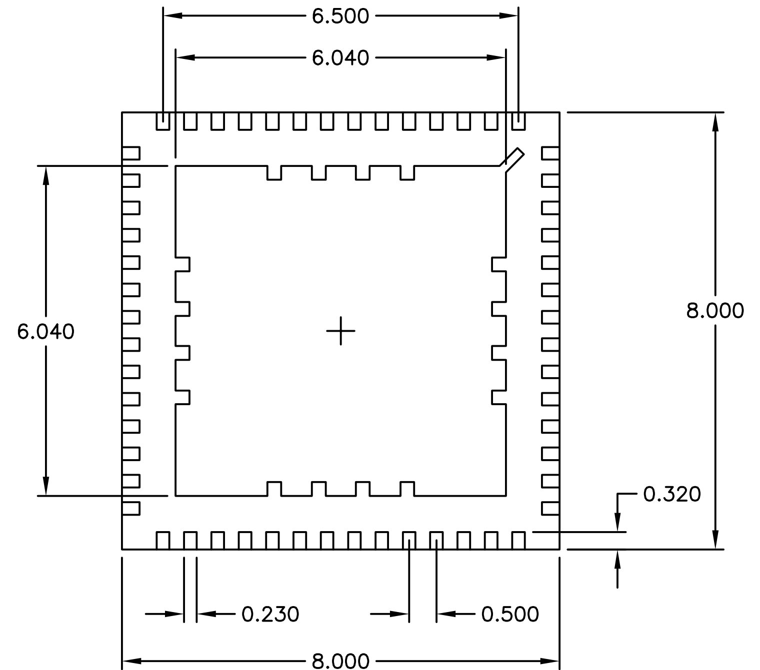
REVISIONS			
ECN NO.	DATE	DESCRIPTION	APPROVED
10503	10/27/05	PRODUCTION RELEASE	D.BENANDO

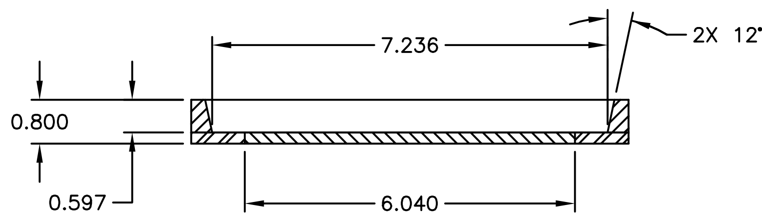


TOP VIEW





BOTTOM VIEW



SECTION A–A

NOTES:
1. BODY: PLASTIC, SEMICONDUCTOR GRADE.
3. LEAD FRAME: COPPER, 194 FH.
4. LEAD FINISH: FULL GOLD PLATE.
5. FRAME THICKNESS: 0.2030 ±.0076.
6. DIE PAD: 6.040 X 6.040.
7. JEDEC OUTLINE: MO–220 (VLLD–5).

THIRD ANGLE PROJECTION

UNLESS OTHERWISE SPECIFIED
DIMENSIONS ARE IN **MILLIMETERS**
TOLERANCES ARE:
X.XX ± 0.15 X.XXXX ± –––
X.XXX ± 0.100 ANGLES: ± 1°

DO NOT SCALE DRAWING

DRAWN BY	W. GRIFFITTS	DATE	10/26/05
APP BY	P. FLASKERUD	DATE	10/26/05
CUSTOMER	–––		

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56 Lead 8mm x 8mm
MLP Open–Pak

SIZE	PART NO.	REV
A	MLP8X8–56–OP–01	3
SCALE NONE	CAD FILE MLP8X8–56–OP–01–R3.DWG	SHEET 1 OF 1